Claims

1. A unified frame that semiconductor front end components may mount to, the unified frame providing a single reference for all the components to align with, comprising:

at least two vertical struts, each said vertical strut having an upper portion, a lower portion, a front face, and a rear face;

an upper support member secured to said top portion of each said vertical strut;

a lower support member secured to said lower portion of each said vertical strut, said lower support member creating a front mounting surface that is secured to said front face, and a rear mounting surface that is secured to said rear face; and

the front end load components mount to said front and rear mounting surface.

2. The unified frame as recited in claim 1, wherein said lower support member further creates a port door/carrier door storage area located between said front mounting surface and said rear mounting surface.

3. The unified frame as recited in claim 1, wherein said upper support member has at least one perforated surface.

4. The unified frame as recited in claim 1, wherein said lower support member has at least one perforated surface.

5. The unified frame as recited in claim 1, wherein each said vertical strut is substantially parallel to each other.

6. A unified frame that semiconductor front end components may mount to, the unified frame providing a single reference for all the components to align with, comprising:

at least two vertical struts, each said vertical strut having an upper portion, a lower portion, a front face, and a rear face;

an upper support member secured to said top portion of each said vertical strut;

a lower support member secured to said lower portion of each said vertical strut, said lower support member creating a front mounting surface that is secured to said front face; and

the front end load components mount to said front mounting surface of said lower support member and said rear face of said vertical strut.

7. The unified structure as recited in claim 6, wherein said upper support member has at least one perforated surface.

8. The unified structure as recited in claim 6, wherein said lower support member has at least one perforated surface.

9. The unified structure as recited in claim 6, wherein each said vertical strut is substantially parallel to each other.

10. A unified frame that semiconductor front end components may mount to, the unified frame providing a single reference for all the components to align with, comprising:

at least two vertical struts, each said vertical strut having an upper portion, a lower portion, a front face, and a rear face;

an upper support member secured to said top portion of each said vertical strut;

a backbone support member secured to said rear face of each said vertical strut,

a front mounting plate secured to said front face of each vertical strut; and

the front end load components mount to said front mounting plate and said backbone support member.

11. A unified frame that semiconductor front end components may mount to, the unified frame providing a single reference for all the components to align with, comprising:

at least two vertical struts, each said vertical strut having an upper portion, a lower portion, a front face, and a rear face;

a component mounting surface having an I/O port, said component mounting surface secured to said top and lower portion of each said vertical strut; and

the front end load components mount to said component mounting surface and said rear face of said vertical strut.

12. A unified frame that semiconductor front end components may mount to, the unified frame providing a single reference for all the components to align with, comprising:

at least two vertical struts, each said vertical strut having a first mounting surface, a second mounting surface, and a third mounting surface, said first, second, and third mounting surface being parallel to each other; and

the front end load components mount to at least one of said first, second, and third mounting surface of said vertical strut.